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(12) **United States Design Patent** (10) **Patent No.:** **US D916,651 S**  
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(54) **SOLAR PANEL**

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**Related U.S. Application Data**

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See application file for complete search history.

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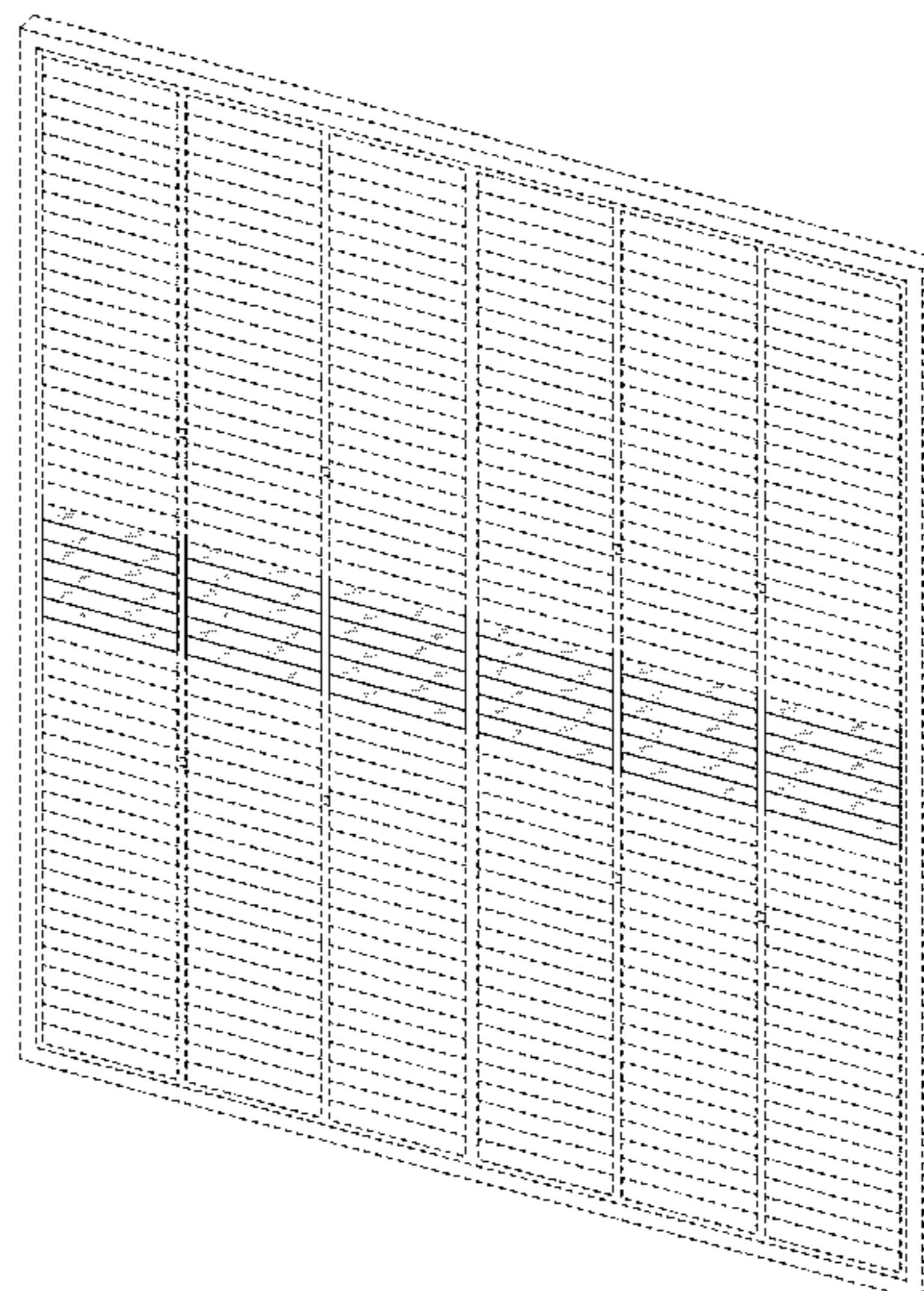
(57) **CLAIM**

The ornamental design for a solar panel, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top, and right side perspective view of a solar panel;  
FIG. 2 is a front elevational view thereof, the rear elevational view forming no part of the claimed design;  
FIG. 3 is a top plan view thereof, the bottom plan view being a mirror image of the top plan view shown;  
FIG. 4 is a left side elevational view thereof, the right side elevational view being a mirror image of the left side elevational view shown; and,  
FIG. 5 is a detail view along line 5-5 in FIG. 2.  
The broken lines show portions of the solar panel that form no part of the claimed design.

**1 Claim, 3 Drawing Sheets**





**Related U.S. Application Data**

14/674,983, filed on Mar. 31, 2015, now Pat. No. 9,947,820, and a continuation-in-part of application No. 14/605,695, filed on Jan. 26, 2015, now Pat. No. 9,484,484, and a continuation-in-part of application No. 14/594,439, filed on Jan. 12, 2015, now Pat. No. 9,397,252, and a continuation-in-part of application No. 14/586,025, filed on Dec. 30, 2014, and a continuation-in-part of application No. 14/585,917, filed on Dec. 30, 2014, now abandoned, and a continuation-in-part of application No. 14/577,593, filed on Dec. 19, 2014, now Pat. No. 9,356,184, and a continuation-in-part of application No. 14/572,206, filed on Dec. 16, 2014, now Pat. No. 9,401,451, and a continuation-in-part of application No. 14/566,278, filed on Dec. 10, 2014, now abandoned, and a continuation-in-part of application No. 14/565,820, filed on Dec. 10, 2014, now abandoned, and a continuation-in-part of application No. 14/560,577, filed on Dec. 4, 2014, now Pat. No. 9,876,132, and a continuation-in-part of application No. 14/552,761, filed on Nov. 25, 2014, now abandoned, and a continuation-in-part of application No. 14/550,676, filed on Nov. 21, 2014, now abandoned, and a continuation-in-part of application No. 29/509,588, filed on Nov. 19, 2014, now Pat. No. Des. 767,484, and a continuation-in-part of application No. 29/509,586, filed on Nov. 19, 2014, now Pat. No. Des. 750,556, and a continuation-in-part of application No. 14/548,081, filed on Nov. 19, 2014, now abandoned, and a continuation-in-part of application No. 14/543,580, filed on Nov. 17, 2014, now Pat. No. 9,882,077, and a continuation-in-part of application No. 14/539,546, filed on Nov. 12, 2014, now abandoned, and a continuation-in-part of application No. 14/536,486, filed on Nov. 7, 2014, now abandoned, and a continuation-in-part of application No. 29/508,323, filed on Nov. 5, 2014, now abandoned, and a continuation-in-part of application No. 14/532,293, filed on Nov. 4, 2014, now abandoned, and a continuation-in-part of application No. 14/530,405, filed on Oct. 31, 2014, now Pat. No. 9,780,253, and a continuation-in-part of application No. 29/506,755, filed on Oct. 20, 2014, now abandoned, and a continuation-in-part of application No. 29/506,415, filed on Oct. 15, 2014.

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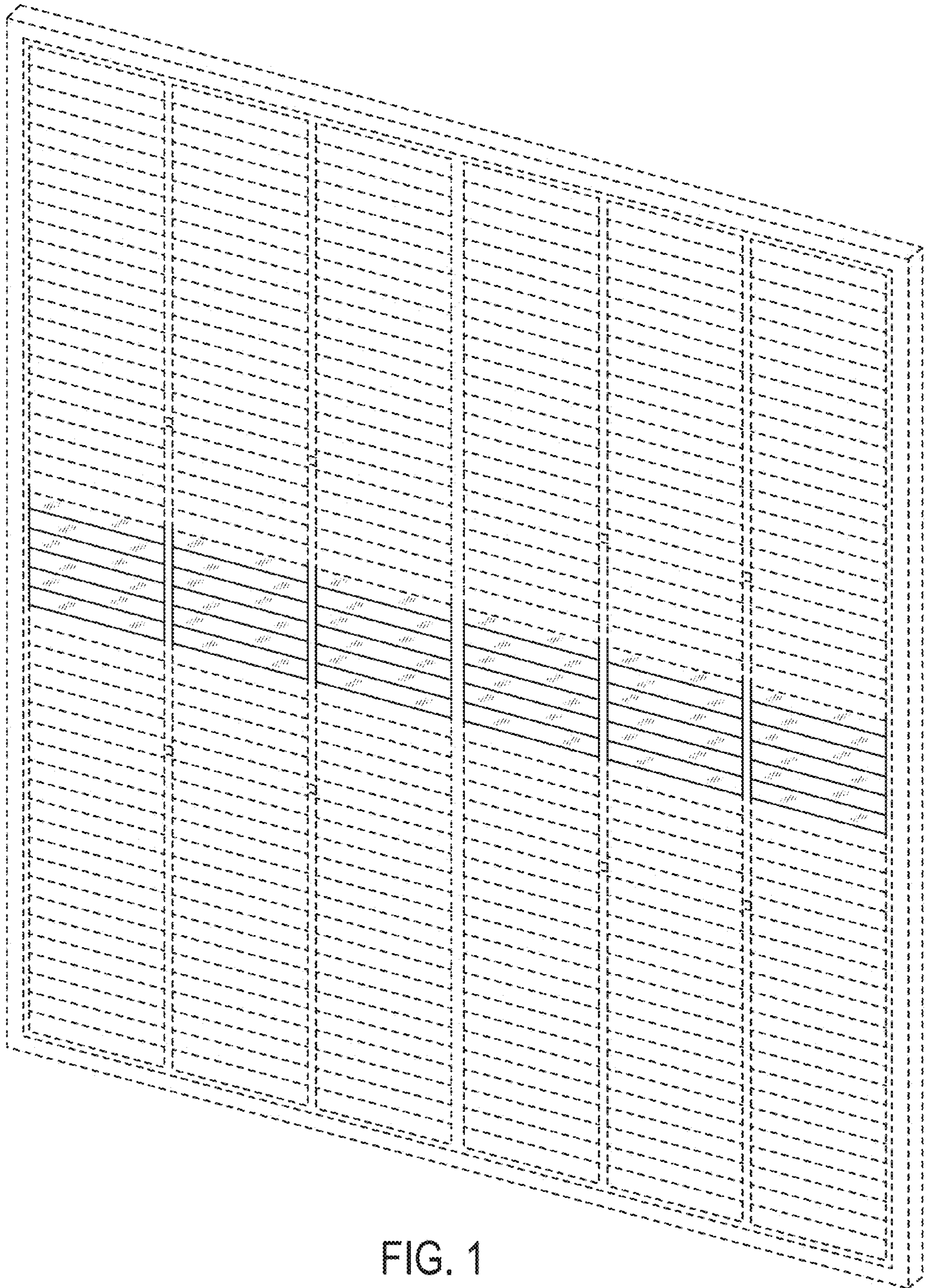


FIG. 1

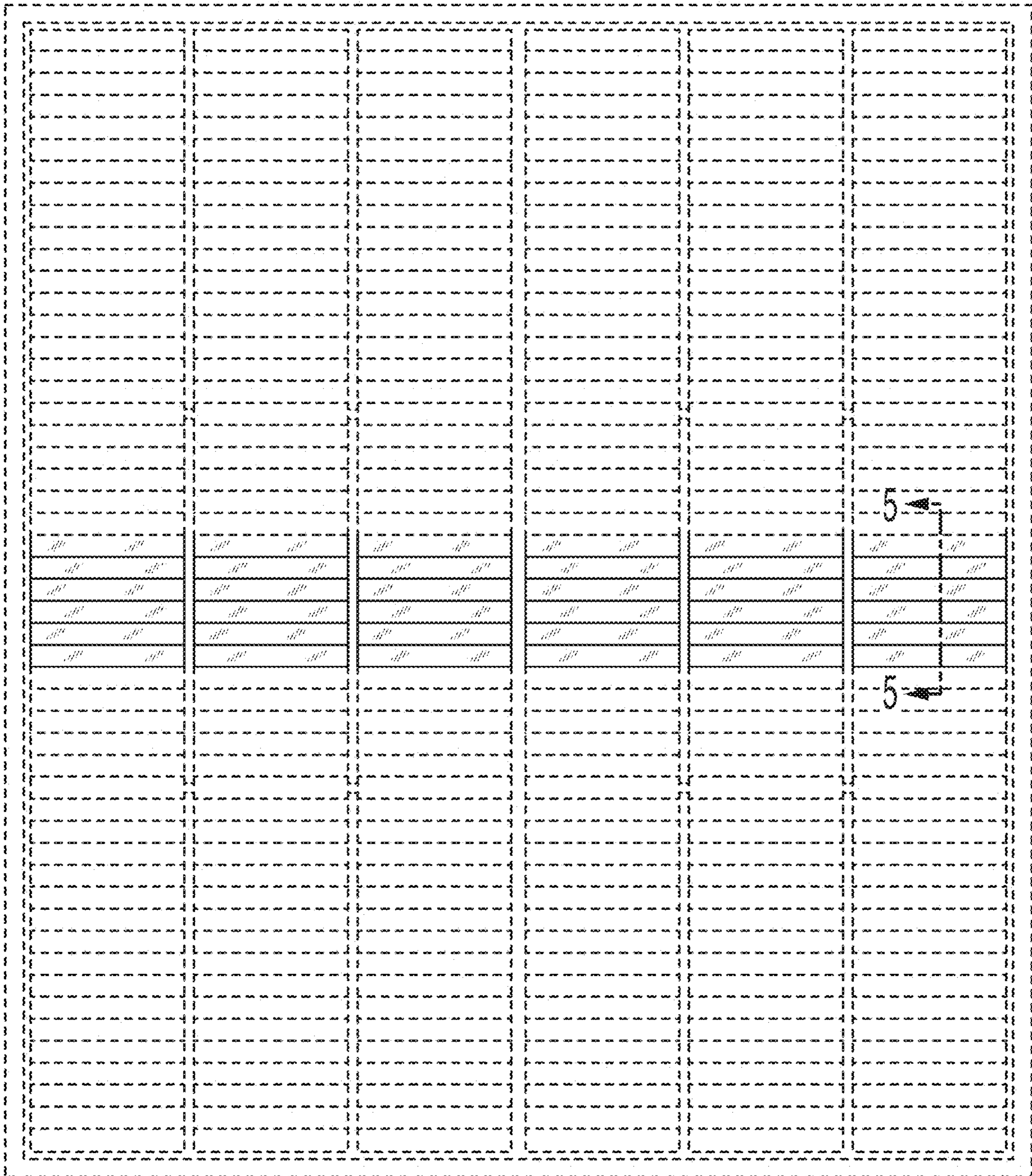


FIG. 2



FIG. 3

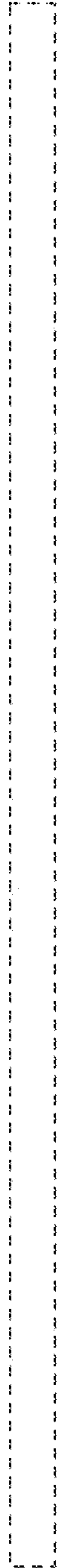


FIG. 4



FIG. 5